ALL ARTWORK VIEWED FROM TOP SIDE
ALL ARTWORK VIEWED FROM TOP SIDE

<table>
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<tr>
<th>LAYER NAME</th>
<th>PMP4482</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
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<td>TEXAS INSTRUMENTS</td>
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ALL ARTWORK VIEWED FROM TOP SIDE

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ALL ARTWORK VIEWED FROM TOP SIDE
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<td>TEXAS INSTRUMENTS</td>
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</tbody>
</table>
ALL ARTWORK VIEWED FROM TOP SIDE

Symbol | Quantity | Finished Hole Size | Plated | Hole Type
---|---|---|---|---
\(\bigcirc\) | 66 | 5.00mil (0.127mm) | PTH | Round
\(\bigcirc\) | 12 | 7.87mil (0.200mm) | PTH | Round
\(\diamondsuit\) | 24 | 15.00mil (0.381mm) | PTH | Round
\(\heartsuit\) | 64 | 28.00mil (0.711mm) | PTH | Round
\(\spadesuit\) | 21 | 39.37mil (1.000mm) | PTH | Round
\(\downarrow\) | 10 | 40.00mil (1.016mm) | PTH | Round

187 Total

PMP4482 | REV: A | SUN REV: Not In VersionControl
---|---|---
LAYER NAME = Drill Drawing | TID #: PMP4482 |
PLOT NAME = Drill Drawing | GENERATED: 4/1/2016 6:05:59 PM | TEXAS INSTRUMENTS
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